



Final Product Change Notification

201409017F01

Issue Date: 10-Mar-2015

Effective Date: 22-Jun-2015

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QUALITY

Management Summary

Change of bond wire material from Au to Cu for transistors in SOT223 package.

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu for transistors in SOT223 package

Details of this Change

Scheduled change affect some transistors in SOT223 package.

The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of change to copper wire as given by implementation date below. Gold wire remains qualified for supply security reasons only.

Old product: Bond wire material is gold (Au).

Changed product: Bond wire material is copper (Cu) or gold (Au).

The design and materials of all other components will remain unchanged: die, die attach, mold compound and lead frame. Reliability qualification and full electrical characterization have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages.

Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Top side marking

Products can be identified by different date code formats on package surface:

Products with gold (Au) wire have a 2-digit date code.

Products with copper (Cu) wire will have a 3-digit date code.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 29-Jun-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201005007F	27-Aug-2010		Change of bond wire material from gold to copper in SOT23 package
201204012F01	12-May-2012	10-Aug-2012	Change of bond wire material from gold to copper in SOT23 package
201409017A	22-Oct-2014		Change of bond wire from Au to Cu for transistors in SOT223 package

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 09-Apr-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Customer Part#	Changed Part 12NC
BSP100,135	934033440135
PBHV8140Z,115	934063482115
PBSS302NZ,135	934059043135
PBSS306NZ,135	934059047135
PBSS304PZ,135	934059052135
PBSS306PZ,135	934059054135
PBSS4021PZ,115	934063394115
PBSS4041NZ,115	934063395115
PBSS4041PZ,115	934063396115
PBHV8215Z,115	934063479115
PBHV9215Z,115	934063481115
PBHV8140Z,115	934063482115
PBHV9540Z,115	934063483115
PBSS306NZ,135	934059047135
PBSS304PZ,135	934059052135
PBSS4041NZ,115	934063395115
PBHV8215Z,115	934063479115
BSP030,115	934043650115